54ACT573 Octal Latch with TRI-STATE® Outputs

Check for Samples: 54ACT573

FEATURES

- **I_{CC} and I_{OZ} reduced by 50%**
- **Inputs and outputs on opposite sides of package allowing easy interface with microprocessors**
- **Useful as input or output port for microprocessors**
- **Functionally identical to 'ACT373**
- **TRI-STATE outputs for bus interfacing**
- **Outputs source/sink 24 mA**
- **'ACT573 has TTL-compatible inputs**
- **Standard Military Drawing (SMD)**
  - **'ACT573: 5962-87664**

DESCRIPTION

The 'ACT573 is a high-speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable ($\overline{OE}$) inputs.

The 'ACT573 is functionally identical to the 'ACT373 but has inputs and outputs on opposite sides.

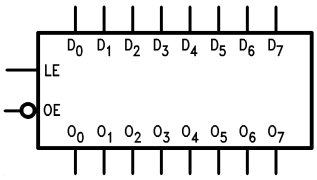
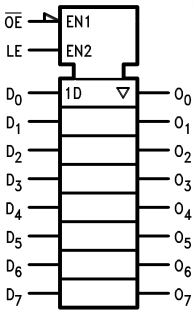


Figure 1. IEEE/IEC



Pin Names	Description
D_0–D_7	Data Inputs
LE	Latch Enable Input
$\overline{OE}$	TRI-STATE Output Enable Input
O_0–O_7	TRI-STATE Latch Outputs

Connection Diagram

Figure 2. Pin Assignment for DIP and Flatpak

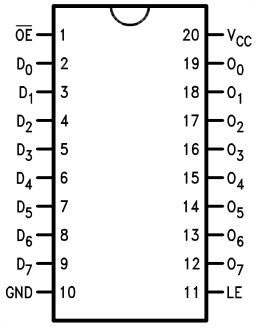
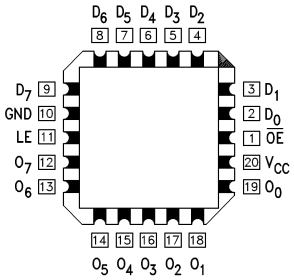


Figure 3. Pin Assignment for LCC



Functional Description

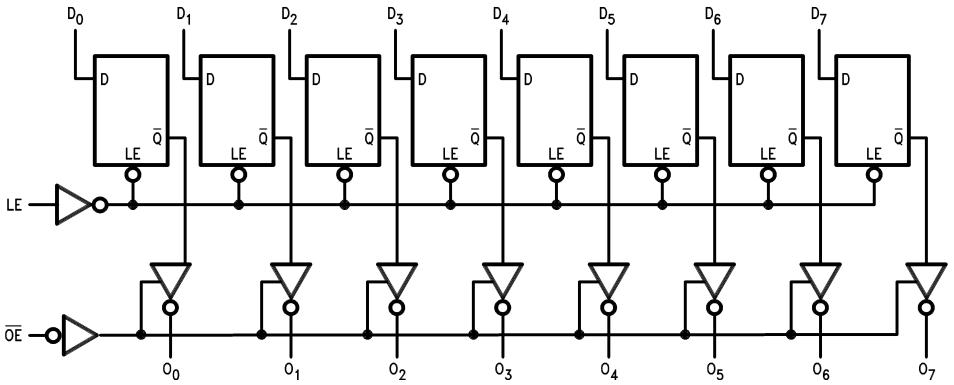
The 'ACT573 contains eight D-type latches with TRI-STATE output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The TRI-STATE buffers are controlled by the Output Enable ($\overline{OE}$) input. When $\overline{OE}$ is LOW, the buffers are enabled. When $\overline{OE}$ is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

Truth Table
(1)

Inputs			Outputs
$\overline{OE}$	LE	D	O_n
L	H	H	H
L	H	L	L
L	L	X	O_0
H	X	X	Z

(1) H = HIGH Voltage
L = LOW Voltage
Z = High Impedance
X = Immaterial
O_0 = Previous O_0 before HIGH-to-LOW transition of Latch Enable

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)

Supply Voltage (V_{CC})	−0.5V to +7.0V
DC Input Diode Current (I_{IK})	
V_I = −0.5V	−20 mA
V_I = V_{CC} + 0.5V	+20 mA
DC Input Voltage (V_I)	−0.5V to V_{CC} + 0.5V
DC Output Diode Current (I_{OK})	
V_O = −0.5V	−20 mA
V_O = V_{CC} + 0.5V	+20 mA
DC Output Voltage (V_O)	−0.5V to V_{CC} + 0.5V
DC Output Source	
or Sink Current (I_O)	±50 mA
DC V_{CC} or Ground Current	
per Output Pin (I_{CC} or I_{GND})	±50 mA
Storage Temperature (T_{STG})	−65°C to +150°C
Junction Temperature (T_J)	
CDIP	175°C

(1) Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. National does not recommend operation of FACT® circuits outside databook specifications.

Recommended OperatingConditions

Supply Voltage (V_{CC})	
'ACT	4.5V to 5.5V
Input Voltage (V_I)	0V to V_{CC}
Output Voltage (V_O)	0V to V_{CC}
Operating Temperature (T_A)	
54ACT	−55°C to +125°C
Minimum Input Edge Rate (ΔV/Δt)	
'ACT Devices	
V_{IN} from 0.8V to 2.0V	
V_{CC} @ 4.5V, 5.5V	125 mV/ns

DC Characteristics for 'ACT Family Devices

			54ACT		
Symbol	**Parameter**	**V_{CC}**	**T_A =**	**Units**	**Conditions**
		(V)	**−55°C to +125°C**		
			Guaranteed Limits		
V_{IH}	Minimum High Level Input Voltage	4.5	2.0	V	V_{OUT} = 0.1V or V_{CC} − 0.1V
		5.5	2.0		
V_{IL}	Maximum Low Level Input Voltage	4.5	0.8	V or V_{CC} − 0.1V	V_{OUT} = 0.1V
		5.5	0.8		
V_{OH}	Minimum High Level Output Voltage	4.5	4.4	V	I_{OUT} = −50 µA
		5.5	5.4		
					(1) V_{IN} = V_{IL} or V_{IH}
		4.5	3.70	V	I_{OH} −24 mA
		5.5	4.70		−24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5	0.1	V	I_{OUT} = 50 µA
		5.5	0.1		
					(1) V_{IN} = V_{IL} or V_{IH}
		4.5	0.50	V	I_{OL} 24 mA
		5.5	0.50		24 mA
I_{IN}	Maximum Input Leakage Current	5.5	±1.0	µA	V_I = V_{CC}, GND
I_{OZ}	Maximum TRI-STATE Leakage Current	5.5	±5.0	µA	V_I = V_{IL}, V_{IH} V_O = V_{CC}, GND
I_{CCT}	Maximum I_{CC}/Input	5.5	1.6	mA	V_I = V_{CC} − 2.1V
I_{OLD}	(2) Minimum Dynamic Output Current	5.5	50	mA	V_{OLD} = 1.65V Max
I_{OHD}		5.5	−50	mA	V_{OHD} = 3.85V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	80.0	µA	V_{IN} = V_{CC} or GND

(1) All outputs loaded; thresholds on input associated with output under test.
(2) Maximum test duration 2.0 ms, one output loaded at a time.

AC Electrical Characteristics

			54ACT			
		V_{CC}	T_A = −55°C			Fig.
Symbol	Parameter	(V)	to +125°C		Units	No.
		(1)	C_L = 50 pF			
			Min	Max		
t_{PLH}	Propagation Delay	5.0	1.5	13.5	ns	
	D_m to O_n					
t_{PHL}	Propagation Delay	5.0	1.5	13.5	ns	
	D_n to O_n					
t_{PLH}	Propagation Delay	5.0	1.5	13.0	ns	
	LE to O_n					
t_{PHL}	Propagation Delay	5.0	1.5	12.0	ns	
	LE to O_n					
t_{PZH}	Output Enable Time	5.0	1.5	11.5	ns	
t_{PZL}	Output Enable Time	5.0	1.5	11.0	ns	
t_{PHZ}	Output Disable Time	5.0	1.5	13.5	ns	
t_{PLZ}	Output Disable Time	5.0	1.5	10.5	ns	

(1) Voltage Range 5.0 is 5.0V ±0.5V

AC Operating Requirements

			54ACT		
		V_{CC}	T_A = −55°C		Fig.
Symbol	**Parameter**	**(V)**	**to +125°C**	**Units**	**No.**
		(1)	C_L = 50 pF		
			Guaranteed Minimum		
t_s	Setup Time, HIGH or LOW	5.0	4.5	ns	
	D_n to LE				
t_h	Hold Time, HIGH or LOW	5.0	1.0	ns	
	D_n to LE				
t_w	LE Pulse Width, HIGH	5.0	5.0	ns	

(1) Voltage Range 5.0 is 5.0V ±0.5V

Capacitance

Symbol	Parameter	Typ	Units	Conditions
C_{IN}	Input Capacitance	5.0	pF	V_{CC} = OPEN
C_{PD}	Power Dissipation	25.0	pF	V_{CC} = 5.0V
	Capacitance			

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